

**ENCAPSULANTS FOR PROTECTING MEMS DEVICES DURING  
POST-PACKAGING RELEASE ETCH**

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**ABSTRACT OF THE DISCLOSURE**

10       The present invention relates to methods to protect a MEMS or microsensor device  
through one or more release or activation steps in a "*package first, release later*"  
manufacturing scheme: This method of fabrication permits wirebonds, other interconnects,  
packaging materials, lines, bond pads, and other structures on the die to be protected from  
physical, chemical, or electrical damage during the release etch(es) or other packaging steps.  
Metallic structures (e.g., gold, aluminum, copper) on the device are also protected from  
15   galvanic attack because they are protected from contact with HF or HCL-bearing solutions.